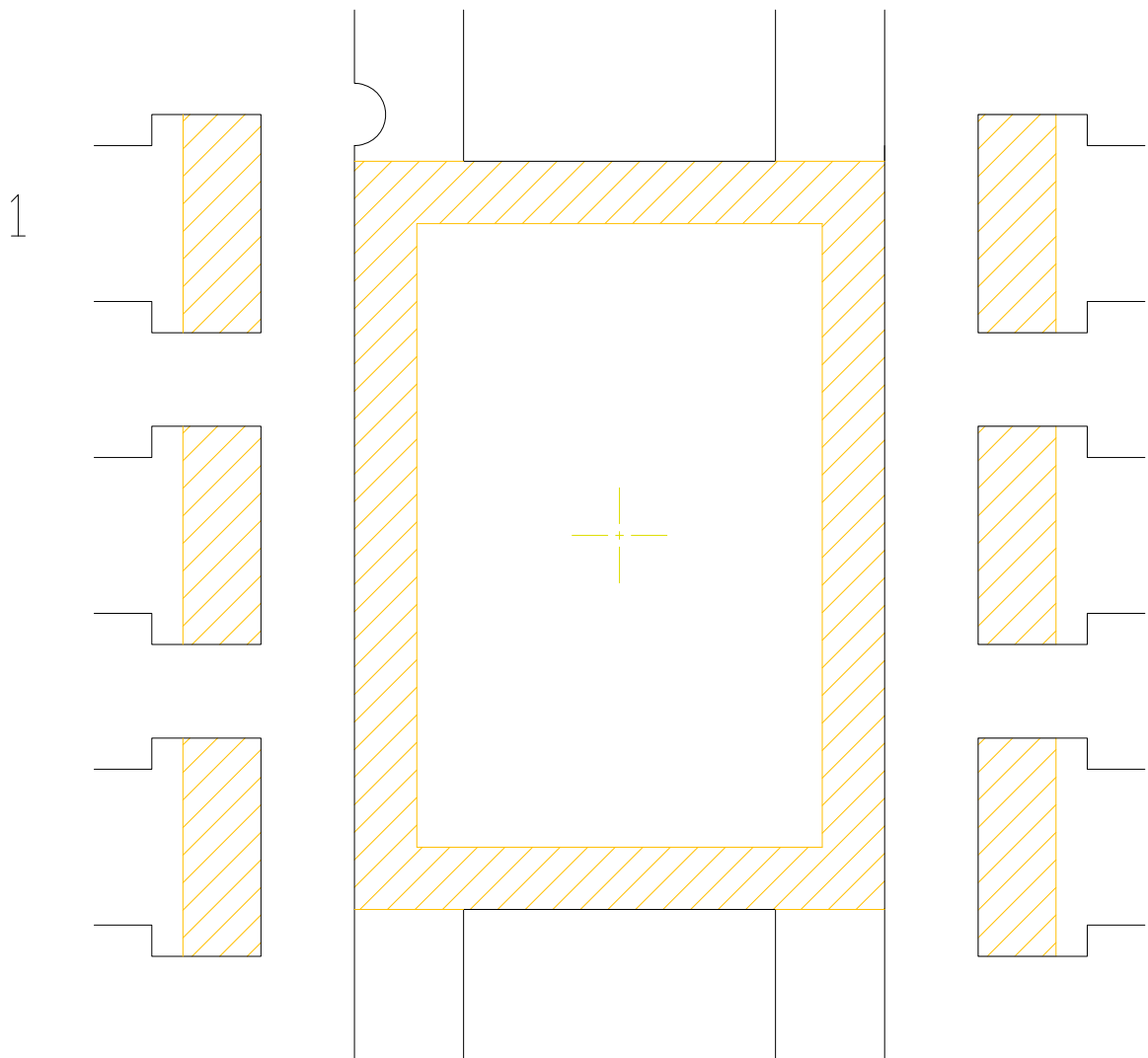


REVISIONS		
REV	DESCRIPTION	DATE
B	INITIAL RELEASE	4-1-2016



 NiPdAu PLATING

ALL INFORMATION CONTAINED HEREIN IS THE PROPERTY OF PROMEX, INC. AND IS CONSIDERED PROPRIETARY AND SUBJECT TO RETURN UPON DEMAND. ACCEPTANCE AND RETENTION HEREOF SIGNIFIES AGREEMENT BY THE RECIPIENT THAT THE INFORMATION WILL NOT BE DISCLOSED TO OTHERS NOR USED CONTRARY TO THE INTEREST OF PROMEX, INC. WITHOUT PRIOR WRITTEN PERMISSION.

CUSTOMER: xxxxx	DOCUMENT #:	<b>PROMEX INDUSTRIES INC.</b> www.promex-ind.com
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 0.85 x 1.20 mm	
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 0.70 x 1.20 mm	TITLE DFN 6L 1.5x1.5 mm 0.50 PITCH BOND SHELL
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	LEADFRAME P/N: 235-00207
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	REV A
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	DO NOT SCALE
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	FILE NAME 6L-DFN-1.5X1.5-50P-BD.DWG
		SHEET 1 of 1